

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (withdrawn) A semiconductor resin mold comprising:
a resin molding cavity having an attachment surface to which a resin tape substrate with a semiconductor chip mounted thereon is attached; and
a plurality of suction holes opened in said attachment surface and connectable to a suction system.
2. (withdrawn) The semiconductor resin mold according to claim 1, further comprising an upper mold member; and a lower mold member assembled with the upper mold member to define said cavity.
3. (withdrawn) The semiconductor resin mold according to claim 1, wherein said plurality of suction holes are disposed in a middle portion of said attachment surface and in a periphery of the middle portion.
4. (withdrawn) The semiconductor resin mold according to claim 3, wherein said suction holes have the same size.
5. (withdrawn) The semiconductor resin mold according to claim 1, further comprising a plurality of slits formed in said attachment surface, wherein said suction holes have openings disposed in the plurality of slits.
6. (withdrawn) The semiconductor resin mold according to claim 3, further comprising a plurality of slits formed in said attachment surface, wherein said suction holes have openings disposed in the plurality of slits.

7. (withdrawn) The semiconductor resin mold according to claim 3, wherein said suction holes in the middle portion of said attachment surface and said suction holes in the peripheral portion of said attachment surface are connectable to different suction systems.

8. (withdrawn) The semiconductor resin mold according to claim 7, wherein said different suction systems are driven successively by a control circuit at a predetermined time interval.

9. (withdrawn) The semiconductor resin mold according to claim 5, wherein said suction hole in the middle portion of said attachment surface and said suction hole in a periphery of the middle portion are formed independently to be connectable to different suction systems.

10. (withdrawn) The semiconductor resin mold according to claim 9, wherein said different suction systems are driven successively by a control circuit at a predetermined time interval.

11. (currently amended) A semiconductor resin molding method of sealing a mount portion of a semiconductor chip on a resin tape substrate with a resin molded body excluding a back surface of the resin tape substrate, said method comprising:

preparing a mold comprising a cavity having a plurality of suction holes connectable to a suction system in an attachment surface to which said resin tape substrate is attached, the plurality of suction holes being grouped into a first group of suction holes and a second group of suction holes;

attaching said resin tape substrate to the attachment surface of the cavity of said mold;

sucking/fixing said resin tape substrate to the attachment surface of said cavity after the step of attaching said resin tape substrate to the attachment surface by first sucking the resin tape substrate through the first group of suction holes and then sucking the resin tape substrate through the second group of suction holes after a lapse of a predetermined time interval; and

supplying a resin into the cavity of said mold after the step of sucking/fixing said resin tape substrate onto the attachment surface.

12. (currently amended) The semiconductor resin molding method according to claim 11, wherein the first group of said plurality of suction holes are disposed in a middle portion of said attachment surface and the second group being in a periphery of the middle portion.

13. (original) The semiconductor resin molding method according to claim 11, wherein said suction holes are disposed in a plurality of slits formed in said attachment surface.

14. (original) The semiconductor resin molding method according to claim 12, wherein said suction holes have openings disposed in a plurality of slits formed in said attachment surface.

15. (currently amended) The semiconductor resin molding method according to claim 12, wherein said first group of suction holes in the middle portion of said attachment surface and said second group of suction holes in a periphery of the middle portion are connectable to different suction systems.

16. (original) The semiconductor resin molding method according to claim 14, wherein said suction holes in the middle portion of said attachment surface and said

suction holes in a periphery of the middle portion are connectable to different suction systems.

17. (currently amended) The semiconductor resin molding method according to claim 15, wherein said step of sucking/fixing said resin tape substrate attached to the attachment surface of said cavity comprises:

sucking/fixing the middle portion of said resin tape substrate by said first group of suction hole holes in the middle portion of said attachment surface; and

subsequently sucking/fixing said resin tape substrate by said second group of suction hole holes in the periphery of the middle portion of said attachment area surface.

18. (original) The semiconductor resin molding method according to claim 15, wherein said different suction systems are driven at a predetermined time interval.

19. (original) The semiconductor resin molding method according to claim 16, wherein said different suction systems are driven at a predetermined time interval.